



- SPECIFICATIONS:**
- ELECTRICAL CHARACTERISTICS:**
    - 1-1. CURRENT RATING: 1.8A for VBUS AND GND, AND 0.25A FOR ALL OTHER CONTACTS
    - 1-2. CONTACT RESISTANCE: 30mΩ MAX.
    - 1-3. INSULATION RESISTANCE: 100MΩ MIN.
    - 1-4. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE.
  - MECHANICAL CHARACTERISTICS:**
    - 2-1. INSERTION FORCE: 35N MAX.
    - 2-2. WITHDRAWAL FORCE: 9.8N MIN. After durability: 8N Min
    3. LIFE TEST: 5,000 CYCLES.
    4. TEMPERATURE RANGE: -50°C TO +80°C.
    5. TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
    6. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
    7. PACKAGE: SEE "2UB1763-000311F" PACKAGE.
    8. FOR REFLOW SOLDERING LEAD-FREE PROCESS.
    9. OTHER GENERAL SPEC. TO REFER "2UB1763-000311F SPEC".

		PIN NO.:		SIGNAL NAME
D1	C1	B1	A1	VBUS
D2	C2	B2	A2	D-
D3	C3	B3	A3	D+
D4	C4	B4	A4	GND
D5	C5	B5	A5	StDA_SSRX-
D6	C6	B6	A6	StDA_SSRX+
D7	C7	B7	A7	GND_DRAIN
D8	C8	B8	A8	StDA_SSTX-
D9	C9	B9	A9	StDA_SSTX+

I	BACK COVER 2	1	LCP UL 94V-0	BLACK
H	BACK COVER 1	1	LCP UL 94V-0	BLACK
G	HOUSING-B	1	PA9T UL 94V-0	BLACK
F	HOUSING-A	1	PA9T UL 94V-0	BLACK
E	USB3 CONTACT	20	C2680	30±0.02 PLATING ON CONTACT AREA, MATTE Sn 80%MIN. ON SOLDERING AREA, 50μ" MIN. NICKEL UNDER PLATING OVERALL
D	USB2 CONTACT	16	C5191	30±0.02 PLATING ON CONTACT AREA, MATTE Sn 80%MIN. ON SOLDERING AREA, 50μ" MIN. NICKEL UNDER PLATING OVERALL
C	FINGER	3	SUS201	CLEAN
B	REAR SHELL	1	SUS201	CLEAN
A	FRONT SHELL	1	SUS201	40μ" MIN PLATING ONLY AT KINKS AND PLATING AT THE OTHER AREAS
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:	TITLE	FOUR LAYERS OF USB3,+3.0 36PIN DIP TYPE
X : ±0.5	X : ±2°	DWN	PART NO. 2UB1763-000311F
X.X : ±0.3	X.X : ±1°	CHKD	SCALE N/A UNIT: mm
X.XX : ±0.2		APVD	SIZE: A3 SHEET: 1 OF 1 REV:A

CUSTOMER COPY

信音科技(香港)有限公司